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JP 6-136092

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File: JPAB

May 17, 1994

PUB-NO: JP406136092A
DOCUMENT-IDENTIFIER: JP 06136092 A
TITLE: EPOXY RESIN COMPOSITION

PUBN-DATE: May 17, 1994

INVENTOR-INFORMATION:

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N/A

APPL-NO: JP04312835

APPL-DATE: October 27, 1992

US-CL-CURRENT: 528/407

INT-CL (IPC): C08G 59/24; C08L 63/00

ABSTRACT:

PURPOSE: To provide an epoxy resin composition containing two kinds of diglycidyl ether compounds having specific structures as an epoxy resin, highly improved in weather resistance, and suitable for outdoor coatings, LED-sealing resins loaded on automobiles, etc.

CONSTITUTION: The epoxy resin composition contains (A) an epoxy resin comprising the mixture of 1,4-cyclohexanedimethanol diglycidyl ether (DME) and hydrogenated bisphenol A diglycidyl ether (HBE). The DME and HBE in the component A is preferably mixed in a DME/HBE weight ratio of 30/70 to 60/40. The component B is preferably an aliphatic polyamine curing agent such as ethylene diamine when the ordinary temperature curing reactivity is required for outside coatings, and is also preferably an acid anhydride curing agent such as phthalic acid anhydride when used for sealing light emitting diodes, etc.

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withdrawn

File 351:DERWENT WPI 1963-1998/UD=9830;UP=9827;UM=9825
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DIALOG(R)File 351:DERWENT WPI
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009842304 **Image available**
WPI Acc No: 94-122160/199415

Bare-chip mounting structure capable of easily detaching chip - forms
insulating layer of thermoplastic synthetic resin between substrate and
bare-chip to fix it and detach it by softening insulating layer

NoAbstract

Patent Assignee: FUJITSU LTD (FUIT)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Main IPC	Week
JP 6069280	A	19940311	JP 92218109	A	19920818	H01L-021/60	199415 B

Priority Applications (No Type Date): JP 92218109 A 19920818

Patent Details:

Patent	Kind	Lan	Pg	Filing Notes	Application	Patent
JP 6069280	A		5			

Abstract (Basic): JP 6069280 A

Dwg.1/4

Derwent Class: U11; U14

International Patent Class (Main): H01L-021/60

2/9/1
DIALOG(R) File 347:JAPIO
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04425380
MOUNTING STRUCTURE FOR BARE CHIP

PUB. NO.: 06-069280 [JP 6069280 A]
PUBLISHED: March 11, 1994 (19940311)
INVENTOR(s): KUSAYA TOSHIHIRO
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APPLICANT(s): FUJITSU LTD [000522] (A Japanese Company or Corporation), JP
(Japan)
APPL. NO.: 04-218109 [JP 92218109]
FILED: August 18, 1992 (19920818)
INTL CLASS: [5] H01L-021/60; H01L-021/60
JAPIO CLASS: 42.2 (ELECTRONICS -- Solid State Components)
JOURNAL: Section: E, Section No. 1561, Vol. 18, No. 311, Pg. 93, June
14, 1994 (19940614)

ABSTRACT

PURPOSE: To facilitate removal of a bare chip by curing an insulating layer for fixing the chip to a predetermined surface of a board by heating, and further forming it of a synthetic resin material to be softened by heating it to a temperature higher than the predetermined temperature.

CONSTITUTION: The mounting structure for a bare chip comprises a board 8 having pads 3 to be connected to connecting parts 2 through a leader pattern 9 and formed at predetermined surface 1A of an insulating member 1, a bare chip 4 having electrodes 5, and bumps 7 for connecting the pads 3 to the electrodes 5. The chip 4 is fixed to the surface 1A through an insulating layer 6, and the electrodes 5 are so connected as to have conduction with the parts 2. In such a mounting structure of the chip 4, the layer 6 is so cured by heating it to a predetermined temperature T1 as to remove the chip 4 from the board 8 as required and formed of synthetic resin to be softened by heating to a temperature T2 higher than the temperature T1.